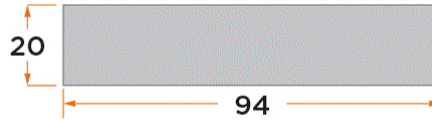


Product features SI

6023-S

Semiconductor casing:	TO-220
Semiconductor mounted by:	Clip Mounting ; Bonding
Material	Silicon w. Glasfibre
Thickness [mm]:	0.23
Insulation capacity:	5.0
Dielectric coefficient	2.0



Further information

Glass fiber reinforced silicone foil in combination with bushes facilitate insulated mounting of semiconductors e.g. on heatsinks. They are highly flexible and ensure optimal heat conductivity even without using thermal compounds. - Custom designed in all configurations (on request). - Cost saving assembly of different components onto a common insulator wafer. - self-adhesive on one side - Thickness: 0,23mm - Dielectric strength: app. 5 KV - Dielectric constant: 2,29 (by 10^6 Hz) - Hardness: (Test ASTM D 2240) 85 Shore A - Elongation: (Test ASTM D 412) 2% - Colour: grey - Tolerance: +/-0,02mm - Temperature range: -60 / +200 °C - Thermal Conductivity: 0,9 W / mK - UL listed

